

RV1S9184Q

R08DS0190EJ0200 Rev.2.00 Mar 09, 2023

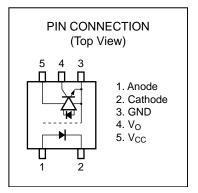
AUTOMOTIVE 1 Mbps, OPEN COLLECTOR OUTPUT, 5-PIN SOP (SO5) PHOTOCOUPLER

DESCRIPTION

The RV1S9184Q is a photocoupler featuring high-speed communication with open-collector output which consists of an AlGaAs LED on the input side and a one-chip signal processing circuit with built-in photo diode on the output side. The package is a small outline package (SOP) type and has a shield effect to cut the ambient light. The RV1S9184Q is designed specifically for high voltage isolation and wide temperature operation (-40 to +135 °C), which is suitable for automotive application.

FEATURES

- Operating ambient temperature ($T_A = -40 \text{ to } +135 \text{ °C}$)
- High isolation voltage (BV = 3 750 Vr.m.s.)
- High speed response (tphL = 700 ns MAX., tpLH = 700 ns MAX., PWD = 500 ns MAX.)
- High common mode transient immunity (CM_H, CM_L = ± 15 kV/ μ s MIN.)
- Small package (SO5)
- Pb-free product
- AEC-Q100 (Grade 1: $T_A = -40$ to +125 °C) compliant
- Safety standard
- • UL: UL1577, Double protection

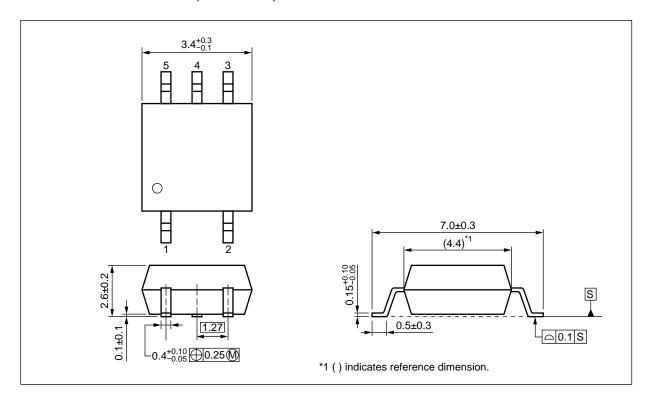


APPLICATIONS

Consumer Vehicle

Start of mass production Feb.2020

PACKAGE DIMENSIONS (UNIT: mm)

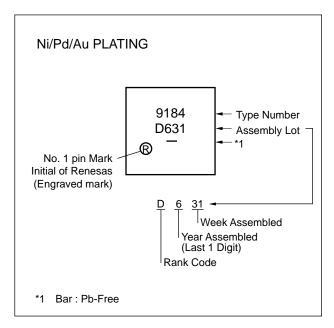


Weight: 0.08 g (TYP.)

PHOTOCOUPLER CONSTRUCTION

Parameter	MIN.
Air Distance	4.2 mm
Creepage Distance	4.2 mm
Isolation Distance	0.2 mm

MARKING EXAMPLE



ORDERING INFORMATION

Part Number	Order Number	Solder Plating	Packing Style	Safety Standard	Application Part
		Specification		Approval	Number *1
RV1S9184QKCSP- 1000	RV1S9184QKCSP- 1000#SC0/D	Pb-Free (Ni/Pd/Au)	Embossed Tape 20 pcs	Standard Products (UL Approved)	RV1S9184Q
	RV1S9184QKCSP- 1000#KC0/D	,	Embossed Tape 2 500 pcs/reel		

Notes: *1. For the application of the safety standard, the following part number should be used.

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current *1	l _F	25	mA
	Reverse Voltage	V_{R}	5	V
Detector	Supply Voltage	Vcc	−0.5 to +30	V
	Output Voltage	Vo	−0.5 to V _{CC}	V
	Output Current	lo	15	mA
	Power Dissipation *2	Pc	100	mW
Isolation Voltage *3		BV	3 750	Vr.m.s.
Operating Ambient Temperature		TA	−40 to +135	°C
Storage Temperature		T_{stg}	−55 to +150	°C

Notes: *1. Reduced at a rate of 0.5 mA/ $^{\circ}$ C above T_A = 115 $^{\circ}$ C.

- *2. Reduced at a rate of 1.5 mW/°C above $T_A = 75$ °C.
- *3 AC voltage for 1 minute at T_A = 25 °C, RH = 60 % between input and output.

Pins 1–2 shorted together, 3-4 shorted together.

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Supply Voltage	Vcc	4.5	15	20	V
Output Voltage	Vo	0		20	V
Forward Current (ON) *1	I _{F(ON)}	6		20	mA
Forward Voltage (OFF)	V _{F(OFF)}	0		0.8	V

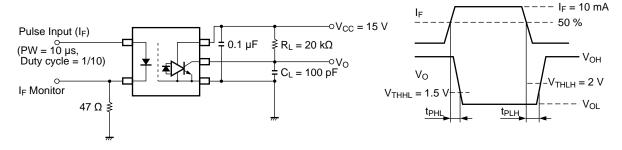
Notes: *1. Forward current at T_A = 115 °C or more should not exceed absolute maximum ratings.

ELECTRICAL CHARACTERISTICS (T_A = - 40 to + 135 °C, unless otherwise specified)

	Parameter	Symbol	Conditions	MIN.	TYP. *1	MAX.	Unit
Diode	Forward Voltage	VF	I _F = 10 mA	1.18	1.65	1.98	V
	Reverse Current	I _R	V _R = 3 V		0.1	100	μΑ
Detector	High Level Output Current	Іон	$I_F = 0 \text{ mA}, V_{CC} = V_0 = 20 \text{ V}$		0.01	50	μΑ
	Low Level Output Voltage	Vol	$I_F = 5 \text{ mA}, I_O = 2 \text{ mA},$		0.1	0.6	V
			V _{CC} = 15 V				
	High Level Supply Current	I _{CCH}	$I_F = 0 \text{ mA}, V_{CC} = 15 \text{ V}$		0.9	1.6	mA
	Low Level Supply Current	I _{CCL}	$I_F = 10 \text{ mA}, V_{CC} = 15 \text{ V}$		0.9	1.6	mA
Coupled	Threshold Input Current	I _{FHL}	$V_{CC} = 15 \text{ V}, V_{O} = 0.6 \text{ V},$			3.5	mA
	$(H \rightarrow L)$		Io = 2 mA				
	Isolation Resistance	R _{I-O}	V _{I-O} = 500 V _{DC} ,	10 ¹⁰			Ω
			RH = 40 ~ 60 %				
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1 MHz		0.5	1.0	pF
	Propagation Delay Time	t _{PHL}	$I_F = 10 \text{ mA}, V_{CC} = 15 \text{ V},$	100	330	700	ns
	$(H \rightarrow L)^{*2}$		V _{THHL} = 1.5 V, V _{THLH} = 2.0 V,				
	Propagation Delay Time	t _{PLH}	$R_L = 20 \text{ k}\Omega, C_L = 100 \text{ pF}$	400	550	700	
	$(L \rightarrow H)^{*2}$						
	Pulse Width Distortion *2	PWD =			220	500	
		tphl-tplh					
	Common Mode	СМн	$T_A = 25 ^{\circ}\text{C}, I_F = 0 \text{mA},$	15			kV/μs
	Transient Immunity at		$V_{CM} = 1.5 \text{ kV}, V_{CC} = 15 \text{ V},$				
	High Level Output *3		$R_L = 20 \text{ k}\Omega, V_O > 3.0 \text{ V},$				
			C _L = 100 pF				
	Common Mode	CML	$T_A = 25 ^{\circ}\text{C}, I_F = 10 \text{mA},$	15			
	Transient Immunity at Low		$V_{CM} = 1.5 \text{ kV}, V_{CC} = 15 \text{ V},$				
	Level Output *3		$R_L = 20 \text{ k}\Omega, V_O < 1.0 \text{ V},$				
			C _L = 100 pF				

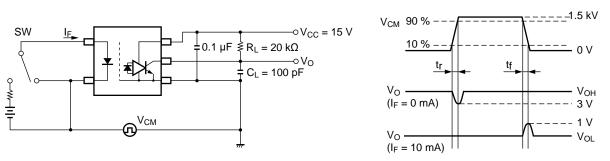
Notes: *1. Typical values at $T_A = 25$ °C

*2. Test circuit for propagation delay time



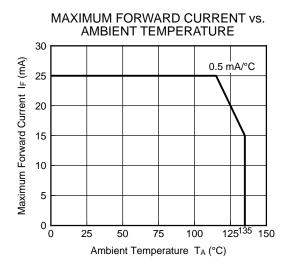
Remark C_L includes probe and stray wiring capacitance.

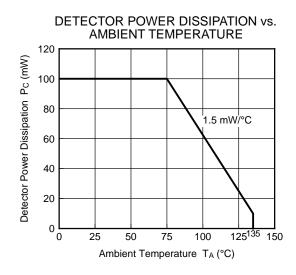
*3. Test circuit for common mode transient immunity

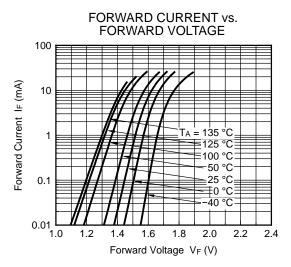


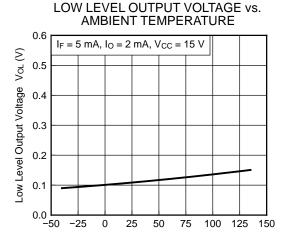
Remark C_L includes probe and stray wiring capacitance.

TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise specified)

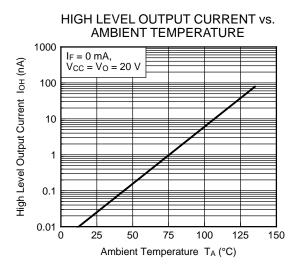


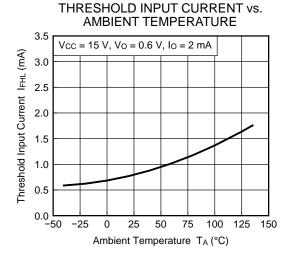




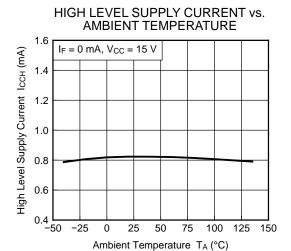


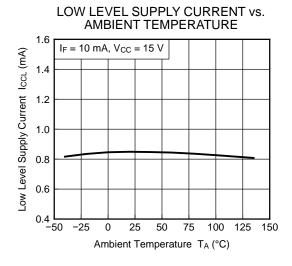
Ambient Temperature TA (°C)

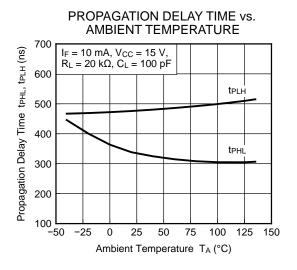


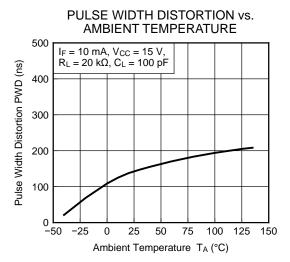


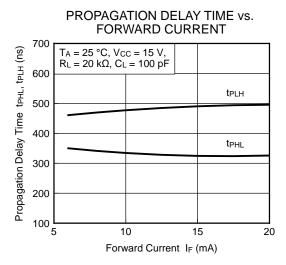
Remark The graphs indicate nominal characteristics.

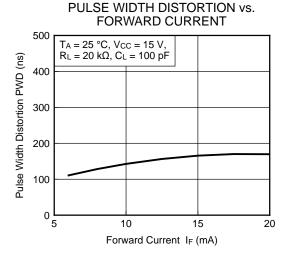






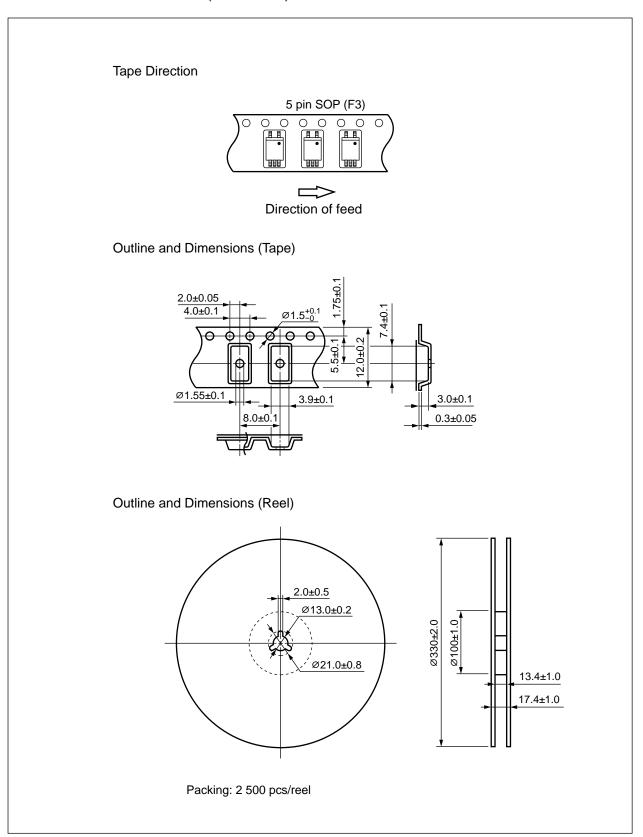




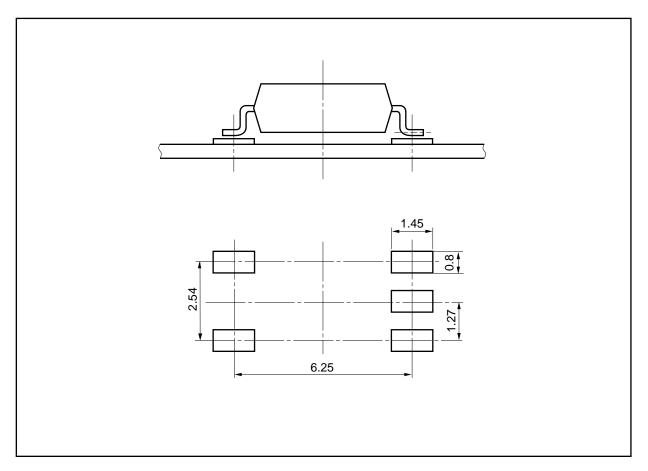


Remark The graphs indicate nominal characteristics.

TAPING SPECIFICATIONS (UNIT: mm)



RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



Remark All dimensions in this figure must be evaluated before use.

NOTES ON HANDLING

- 1. Recommended soldering conditions
 - (1) Infrared reflow soldering

Peak reflow temperature
260 °C or below (package surface temperature)

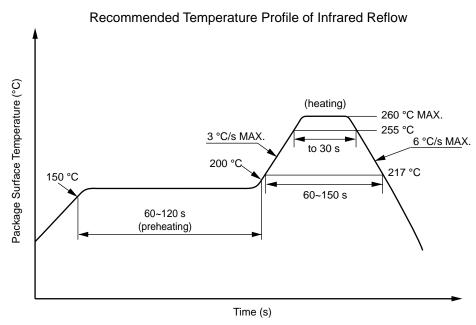
Time of peak reflow temperature -5 °C (255 °C)
Time of temperature higher than 217 °C
30 s or less
60 ~ 150 s

Time of temperature higher than 217 °C
Time to preheat temperature from 150 to 200 °C
60 ~ 150 s
60 ~ 120 s

Number of reflows

• Flux

Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)



JEDEC J-STD-020E compliant soldering conditions

(2) Wave soldering

• Temperature 260 °C or below (molten solder temperature)

• Time 10 s or less

• Preheating conditions 120 °C or below (package surface temperature)

Number of times
Flux
One (Allowed to be dipped in solder including plastic mold portion.)
Rosin flux containing small amount of chlorine (The flux with a maximum

chlorine content of 0.2 Wt % is recommended.)

(3) Soldering by Soldering Iron

Peak temperature (lead part temperature)
Time (per one side)
350 °C or below
3 s or less

Flux
Rosin flux containing small amount of chlorine (The flux with a maximum)

chlorine content of 0.2 Wt % is recommended.)

• Place 1.5 to 2.0 mm or more away from the root of the lead

(4) Cautions

Flux cleaning
Fixing/Coating
Avoid cleaning with Freon- or halogen-based (chlorinated etc.) solvents.
Do not use fixing agents or coatings containing halogen-based substances.

USAGE CAUTIONS

- 1. Be aware that when voltage is applied suddenly between the photocoupler's input and output or between V_{CC} and GND at startup, the output transistor may turn on, even if the voltage is within the absolute maximum ratings.
- 2. By-pass capacitor of more than 0.1 μ F is used between V_{CC} and GND near the device. Also, ensure that the distance between the leads of the photocoupler and capacitor is no more than 10 mm.
- 3. This product is weak for static electricity due to the design of high-speed integrated circuit so protect against static electricity when handling.
- 4. Avoid storage at a high temperature and high humidity.

Caution

GaAs Products

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
 - Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
- 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.

All trademarks and registered trademarks are the property of their respective owners.

Notice

- 1. Descriptions of circuits, software and other related information in this document are provided only to illustrate the operation of semiconductor products and application examples. You are fully responsible for the incorporation or any other use of the circuits, software, and information in the design of your product or system. Renesas Electronics disclaims any and all liability for any losses and damages incurred by you or third parties arising from the use of these circuits, software, or information.
- 2. Renesas Electronics hereby expressly disclaims any warranties against and liability for infringement or any other claims involving patents, copyrights, or other intellectual property rights of third parties, by or arising from the use of Renesas Electronics products or technical information described in this document, including but not limited to, the product data, drawings, charts, programs, algorithms, and application examples.
- 3. No license, express, implied or otherwise, is granted hereby under any patents, copyrights or other intellectual property rights of Renesas Electronics or others
- 4. You shall be responsible for determining what licenses are required from any third parties, and obtaining such licenses for the lawful import, export, manufacture, sales, utilization, distribution or other disposal of any products incorporating Renesas Electronics products, if required.
- 5. You shall not alter, modify, copy, or reverse engineer any Renesas Electronics product, whether in whole or in part. Renesas Electronics disclaims any and all liability for any losses or damages incurred by you or third parties arising from such alteration, modification, copying or reverse engineering.
- 6. Renesas Electronics products are classified according to the following two quality grades: "Standard" and "High Quality". The intended applications for each Renesas Electronics product depends on the product's quality grade, as indicated below.
 - "Standard": Computers; office equipment; communications equipment; test and measurement equipment; audio and visual equipment; home electronic appliances; machine tools; personal electronic equipment; industrial robots; etc.
 - "High Quality": Transportation equipment (automobiles, trains, ships, etc.); traffic control (traffic lights); large-scale communication equipment; key financial terminal systems; safety control equipment; etc.

Unless expressly designated as a high reliability product or a product for harsh environments in a Renesas Electronics data sheet or other Renesas Electronics document, Renesas Electronics products are not intended or authorized for use in products or systems that may pose a direct threat to human life or bodily injury (artificial life support devices or systems; surgical implantations; etc.), or may cause serious property damage (space system; undersea repeaters; nuclear power control systems; aircraft control systems; key plant systems; military equipment; etc.). Renesas Electronics disclaims any and all liability for any damages or losses incurred by you or any third parties arising from the use of any Renesas Electronics product that is inconsistent with any Renesas Electronics data sheet, user's manual or other Renesas Electronics document.

- 7. No semiconductor product is absolutely secure. Notwithstanding any security measures or features that may be implemented in Renesas Electronics hardware or software products, Renesas Electronics shall have absolutely no liability arising out of any vulnerability or security breach, including but not limited to any unauthorized access to or use of a Renesas Electronics product or a system that uses a Renesas Electronics product. RENESAS ELECTRONICS DOES NOT WARRANT OR GUARANTEE THAT RENESAS ELECTRONICS PRODUCTS, OR ANY SYSTEMS CREATED USING RENESAS ELECTRONICS PRODUCTS WILL BE INVULNERABLE OR FREE FROM CORRUPTION, ATTACK, VIRUSES, INTERFERENCE, HACKING, DATA LOSS OR THEFT, OR OTHER SECURITY INTRUSION ("Vulnerability Issues"). RENESAS ELECTRONICS DISCLAIMS ANY AND ALL RESPONSIBILITY OR LIABILITY ARISING FROM OR RELATED TO ANY VULNERABILITY ISSUES. FURTHERMORE, TO THE EXTENT PERMITTED BY APPLICABLE LAW, RENESAS ELECTRONICS DISCLAIMS ANY AND ALL WARRANTIES, EXPRESS OR IMPLIED, WITH RESPECT TO THIS DOCUMENT AND ANY RELATED OR ACCOMPANYING SOFTWARE OR HARDWARE, INCLUDING BUT NOT LIMITED TO THE IMPLIED WARRANTIES OF MERCHANTABILITY, OR FITNESS FOR A PARTICULAR PURPOSE.
- 8. When using Renesas Electronics products, refer to the latest product information (data sheets, user's manuals, application notes, "General Notes for Handling and Using Semiconductor Devices" in the reliability handbook, etc.), and ensure that usage conditions are within the ranges specified by Renesas Electronics with respect to maximum ratings, operating power supply voltage range, heat dissipation characteristics, installation, etc. Renesas Electronics disclaims any and all liability for any malfunctions, failure or accident arising out of the use of Renesas Electronics products outside of such specified ranges.
- 9. Although Renesas Electronics endeavors to improve the quality and reliability of Renesas Electronics products, semiconductor products have specific characteristics, such as the occurrence of failure at a certain rate and malfunctions under certain use conditions. Unless designated as a high reliability product or a product for harsh environments in a Renesas Electronics data sheet or other Renesas Electronics document, Renesas Electronics products are not subject to radiation resistance design. You are responsible for implementing safety measures to guard against the possibility of bodily injury, injury or damage caused by fire, and/or danger to the public in the event of a failure or malfunction of Renesas Electronics products, such as safety design for hardware and software, including but not limited to redundancy, fire control and malfunction prevention, appropriate treatment for aging degradation or any other appropriate measures. Because the evaluation of microcomputer software alone is very difficult and impractical, you are responsible for evaluating the safety of the final products or systems manufactured by you.
- 10. Please contact a Renesas Electronics sales office for details as to environmental matters such as the environmental compatibility of each Renesas Electronics product. You are responsible for carefully and sufficiently investigating applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive, and using Renesas Electronics products in compliance with all these applicable laws and regulations. Renesas Electronics disclaims any and all liability for damages or losses occurring as a result of your noncompliance with applicable laws and regulations.
- 11. Renesas Electronics products and technologies shall not be used for or incorporated into any products or systems whose manufacture, use, or sale is prohibited under any applicable domestic or foreign laws or regulations. You shall comply with any applicable export control laws and regulations promulgated and administered by the governments of any countries asserting jurisdiction over the parties or transactions.
- 12. It is the responsibility of the buyer or distributor of Renesas Electronics products, or any other party who distributes, disposes of, or otherwise sells or transfers the product to a third party, to notify such third party in advance of the contents and conditions set forth in this document.
- 13. This document shall not be reprinted, reproduced or duplicated in any form, in whole or in part, without prior written consent of Renesas Electronics.
- 14. Please contact a Renesas Electronics sales office if you have any questions regarding the information contained in this document or Renesas Electronics products.
- (Note1) "Renesas Electronics" as used in this document means Renesas Electronics Corporation and also includes its directly or indirectly controlled subsidiaries.
- (Note2) "Renesas Electronics product(s)" means any product developed or manufactured by or for Renesas Electronics.

(Rev.5.0-1 October 2020)

Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu, Koto-ku, Tokyo 135-0061, Japan

www.renesas.com

Trademarks

Renesas and the Renesas logo are trademarks of Renesas Electronics Corporation. All trademarks and registered trademarks are the property of their respective owners.

Contact information

For further information on a product, technology, the most up-to-date version of a document, or your nearest sales office, please visit: www.renesas.com/contact/.